ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. 1 international and Pa	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the succession of the s	ubstances s all lowe	within the man r level material	ufacturer liste s for which th	ed item. Not e manufacti	te: if the item urer has engin	is an asseml	oly with low onsibility.
				Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					nation			
Supplier Information														
Company name*			Company unique ID			Unique ID Authority					Response Date*			
onsemi										2024	2024-05-16			
Contact Name Title - Contact			ct		Phone - Contact*				Ema	Email - Contact*				
Product-Env-Stewards Product E			act Enviro Compliance			NA				Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Re			Representative			Phone - Representative*				Ema	Email - Representative*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Pro	Product-Env-Stewards@onsemi.com			
Requester Item Number	tem Number Mfr Item Numbe		Iumber Mfr Item Name			Effective Date	Version]	Manufacturing Site		Weight*	UON	Μ	Unit Type
	FAN536	FAN53611UC123X DC/DC 6MHz Bu		uck 1A	1A 2024			1	MY1		1.25031	mg		Each
Anufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base All		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		re Max Time at Peak Tempera		perature Number of Reflow Cycles				
SnAgCu CU Alloy			1		260		С	30	se	conds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select select a RoHS exemption, if applic sigma range of distribution unless	cable [E] enter the weigh	Requester or Supplier) [B t of the substance or the Pl] select the substance of the substance	ance category (JIG or Requester) or [F] Optionally enter the positive (+	enter a value (Supplier). [C] selec -) and negative (-) tolerance in per	et the substance (J cent (Note: percer	(G) or enter the substa at tolerance values are	nce and CAS (Other). [D] expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.873382	mg	Supplier	Silicon (Si)	7440-21-3		0.8734	mg
Protection coat	0.011543	mg		Polyimide	proprietary data		0.0115	mg
Solder Ball	0.36503	mg	Supplier	Silver (Ag)	7440-22-4		0.0146	mg
			Supplier	Tin (Sn)	7440-31-5		0.3486	mg
			Supplier	Copper (Cu)	7440-50-8		0.0018	mg
Under Bump Metal	3.55E-4	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			В	Nickel (Ni)	7440-02-0		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0	mg